



ESTEE Technology Co., Ltd.
(Group)

益思迪

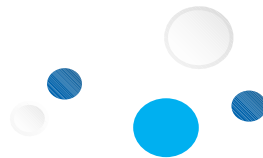


Contents

- ❖ **Company Profile and Overview**
- ❖ **Competitive Advantages**
- ❖ **Technical Services**
- ❖ **Products**
- ❖ **Production & Testing**



Company Profile and Overview





Company Profile



- Founded in 2009, ESTEE Group is a high-tech enterprise specializing in advanced materials and ESD solutions for semiconductor and electronics manufacturing.
- R&D centers in Shenzhen, Shanghai, Zhejiang and Hunan bring together international experts and experienced technical teams.
- The Group owns proprietary intellectual property and multiple ESD product patents, and is now a leading supplier of advanced ESD materials and solutions.
- The Group operates three manufacturing facilities with integrated capabilities spanning materials production, precision processing, automated assembly and testing.
- Its core production lines cover antistatic adhesive products for semiconductor applications, sputtering protection tapes, release liner and protective films, smart ESD monitoring & ionizer instruments, paper and plastic carrier tapes, and precision metal components, supported by slitting, potting, cleanroom injection molding, precision die cutting and tooling capabilities.

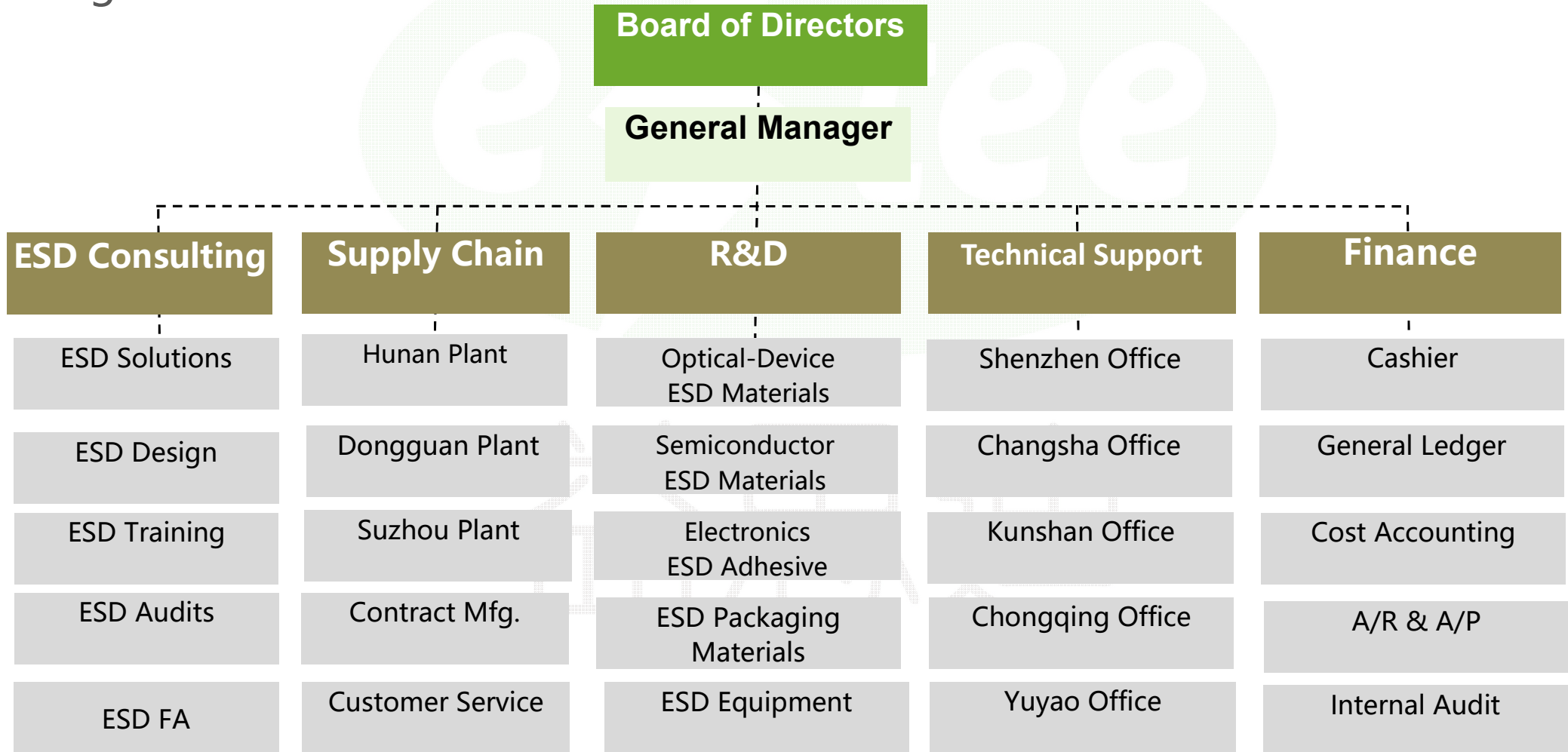




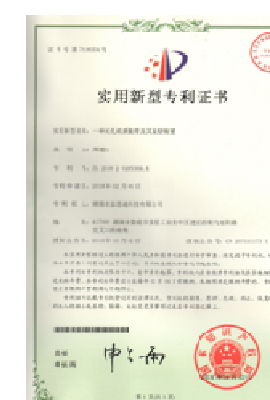
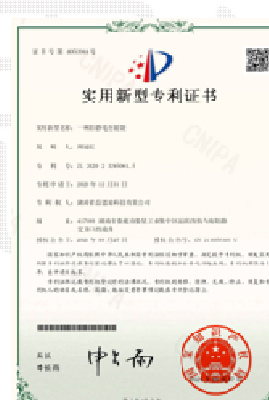
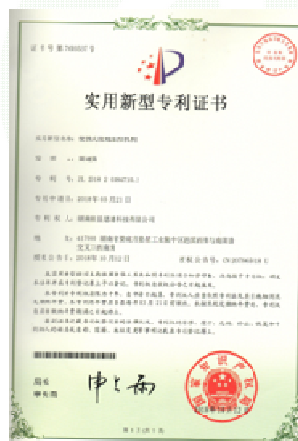
Company Overview



Organizational Structure



Patented Technologies





Company Overview



Quality Assurance: 7 Management Systems, 4 Certificates



ESTEE products are supported by internationally recognized certifications for quality, safety and information-security management—giving customers stronger assurance of product quality and safe use.

ESTEE Products:
The materials are SGS-certified and comply with RoHS and HF standards; the equipment is CE-certified.



Company Overview — Capacity



Product Category	Equipment	Qty.	Output / h	Utilization
Adhesive / Coated Products	Coating Lines	8	900–3,000 m	56%
	Slitting Machines	6	400 rolls	
	Strip-Slitting Machines	3	3,000 m	
	Rewinding Machines	6	3,000 m	
Die Cutting	Press Die-Cutting Machines	4	700 sheets	70%
	Flatbed Die-Cutting Machines	10	2K	51%
	Rotary Die-Cutting Machines	6	1/12–1/24 set	45%



Company Overview — Capacity



Product Category	Equipment / Production Line	Qty.	Output / h	Utilization
Self-Tack Boxes	Box Potting Lines	4	1,000 pcs	70%
	Vacuum Release Tray Assembly Line	4	400–800 pcs	65%
ESD Equipment	SMT Lines	3	1,000 pcs	80%
	DIP Line	1	1,000 pcs	80%
	PCB Assembly Line	1	600 sets	80%
	Grounding Monitor Assembly Line	1	30 sets	55%
	Ionizer Assembly Line	1	60 sets	55%
Cover Tape	Cover Tape Production Lines	2	1,500 m ²	56%



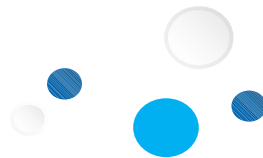
Company Overview — Capacity



Product Category	Equipment / Production Line	Qty.	Output / h	Utilization
Precision Spacers	Stamping & Blanking Lines	6	30–60K	45%
Solder Preforms	Solder Preform Fusion Lines	2	20–100 kg	/
PS Carrier Tape	PS Carrier Tape Lines	6	1,200 m	50%
Paper Carrier Tape	Paper Carrier Tape Lines	6	800 m	70%
Adhesive (50 cc / 30 cc)	Adhesive Cartridge Filling Lines	4	300–500	/

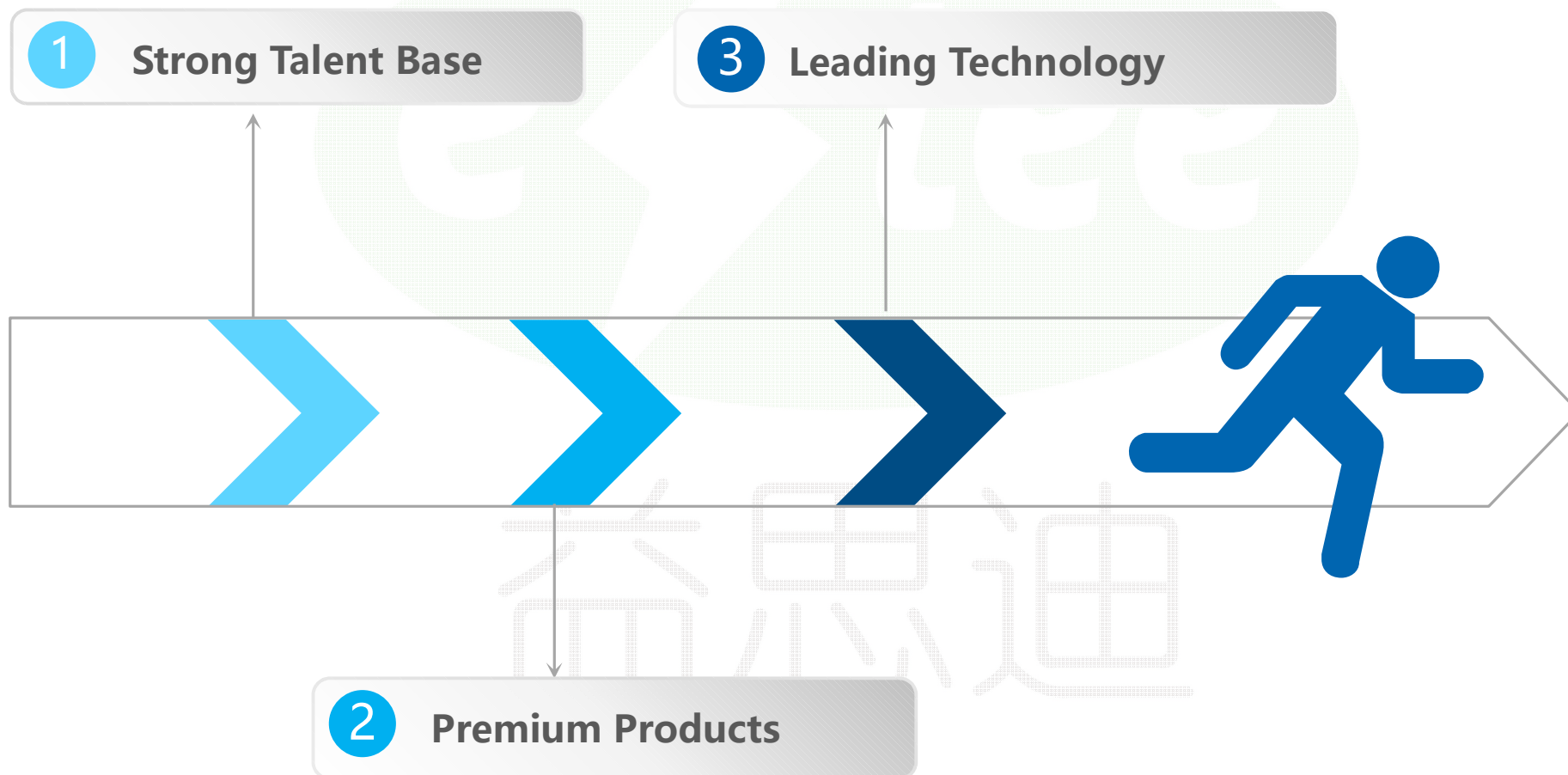


Competitive Advantages





Competitive Advantages





Competitive Advantages



Talent Strength



Our Team

Strong Materials R&D and Engineering Design Team

An experienced product-development team responds rapidly to customer development needs.

R&D Team

Education	Qty.
PhD	2
Master's	10
Bachelor's	20
Total	32

R&D Team

**Team
Synergy**

ENG Team

Engineering Team

Title	Qty.
Senior Engineer	5
Mid-Level Engineer	10
Junior Engineer	12
Total	27

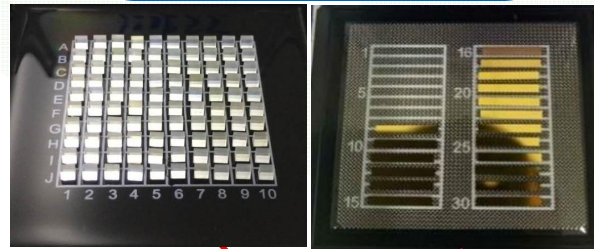


Competitive Advantages



ESD Material Advantages Optical Communications & Aerospace

Optical Devices



Contamination-free
chip packaging boxes



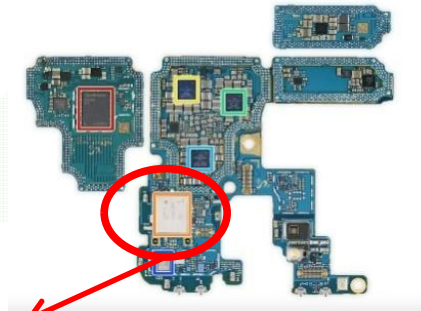


Competitive Advantages

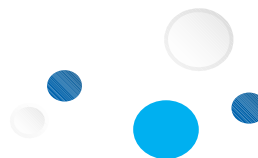


ESD Material Advantages — Premium Smart Devices

EMI Sputtering Process



Sputter protection
tape for phones.





Competitive Advantages

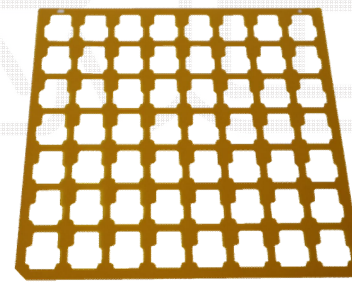
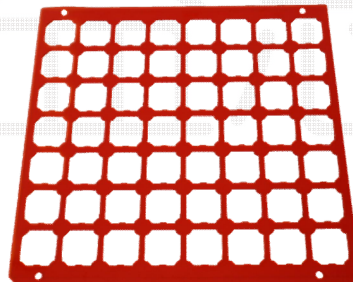
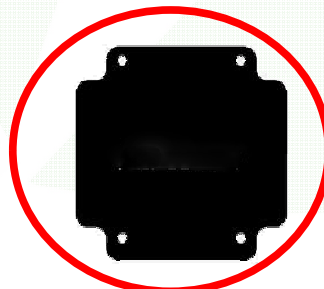


ESD Material Advantages — Premium Smart Devices

EMI Sputtering Process



Sputter protection tape for smart watches.





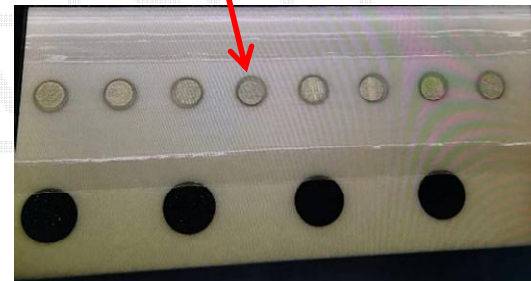
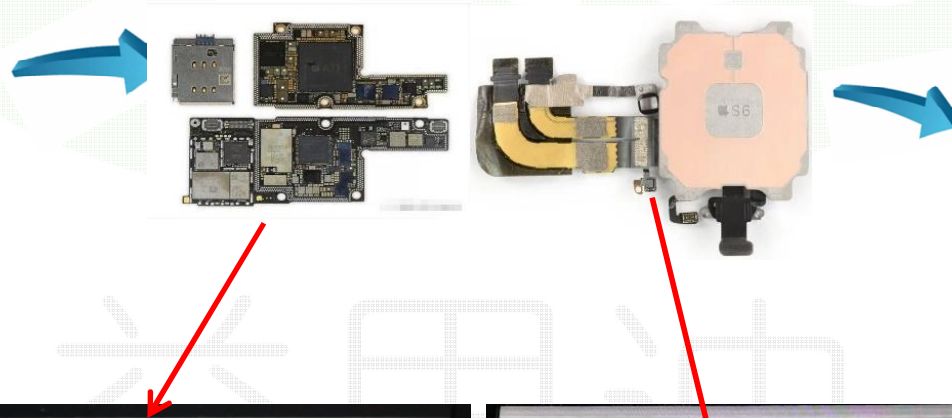
Competitive Advantages



Precision Metal Stamping & Packaging — Smart Devices



Motherboard Spacers

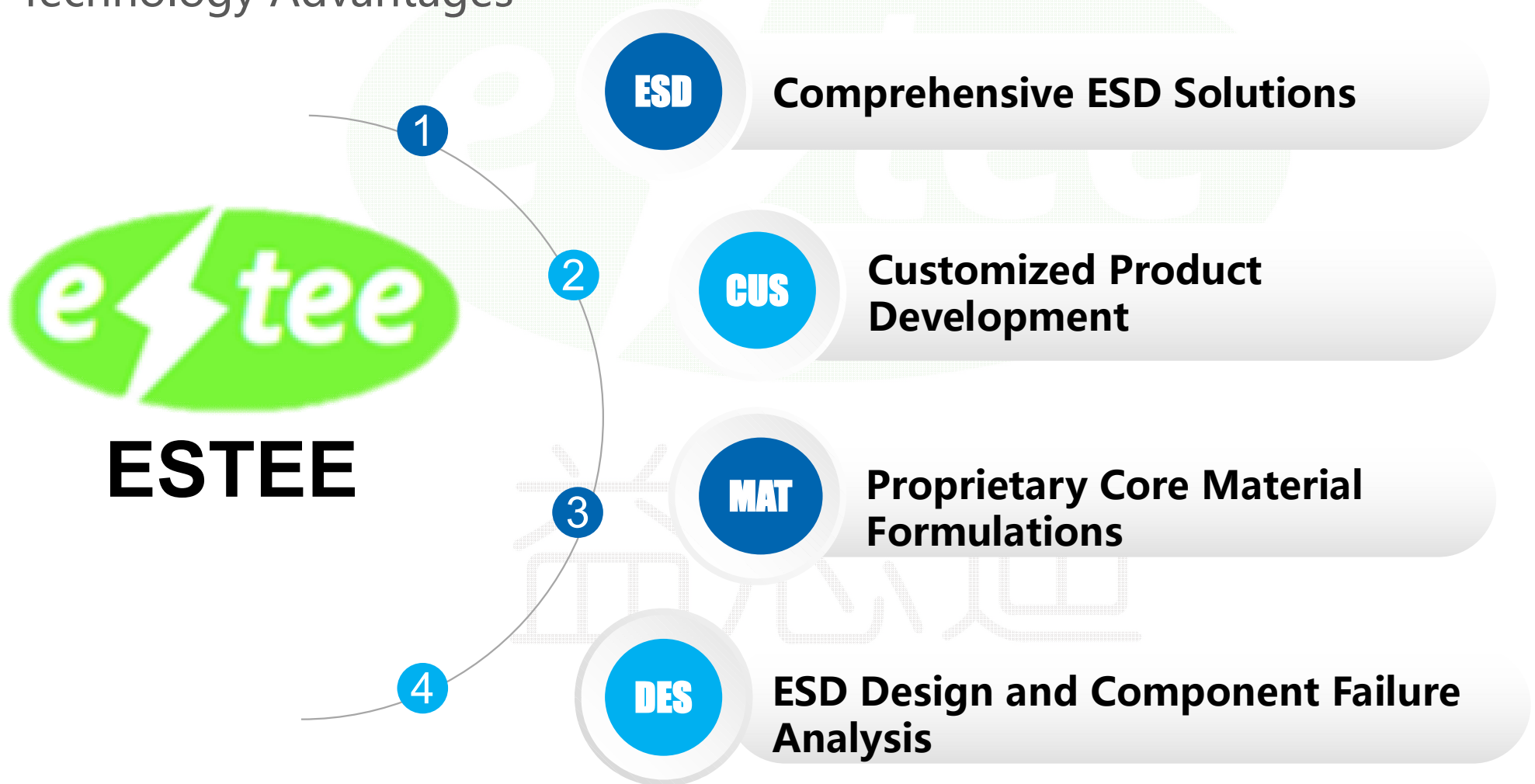




Competitive Advantages



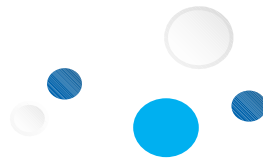
Technology Advantages





ESD Service

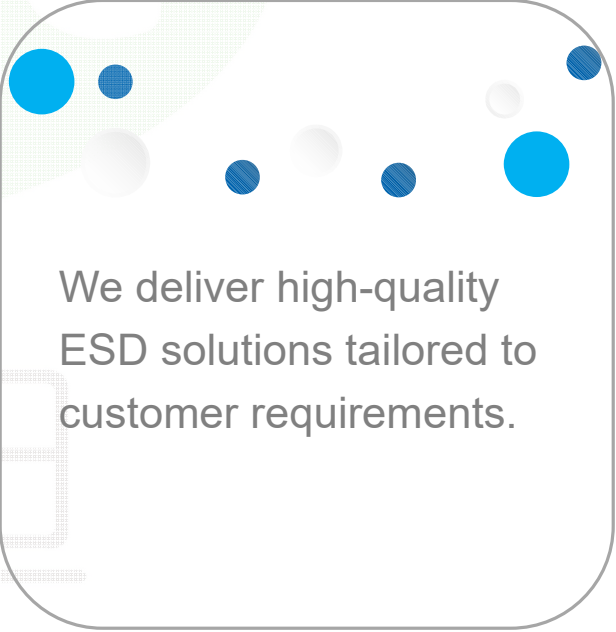
益忠迪





Leading ESD Solutions

- **ESD Control Program Design**
- **ESD Troubleshooting**
- **In-House Training**
- **ANSI/ESD S20.20 Pre-Assessment Support**
- **Second-Party Program Assessments & Audits**



We deliver high-quality ESD solutions tailored to customer requirements.

04



Products

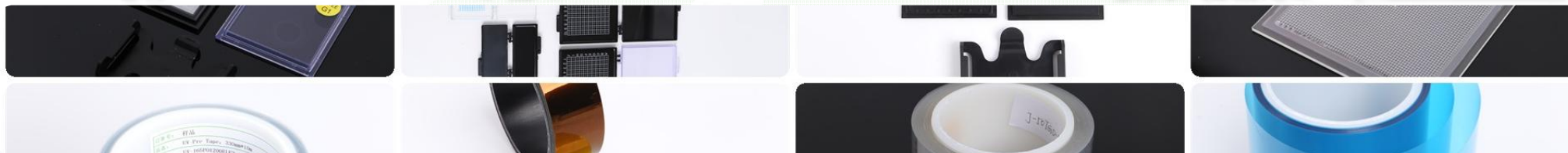
益思迪





Products

Six Integrated Product Systems



01

Precision Chip & Component Handling

VR Vacuum Release Trays / Glue Boxes
Waffle Packs / Grip Rings & Shipping Boxes

02

Semiconductor Packaging Materials

Sputter Process Tapes
UV Dicing Tape / QFN Process Tape

03

Electronics Tapes & Precision Die Cutting

Camera-Module / FPC Tapes
Antistatic PET Release Film
Precision Die Cutting / Multi-Layer Laminates

04

Precision Metal & Automated Packaging

Precision Spacers / Alloy Solder Preforms
Cover Tape / Paper & PS Carrier Tape

05

Industrial Adhesives & Bonding

Epoxy / Acrylic / Silicone / Polyurethane

06

Smart ESD Systems & Services

Grounding Monitors / Ionizers / Networked Monitoring
Program Design / Training / Audits / Improvement

ESD capability spans materials, packaging, equipment and services — with application-specific customization.

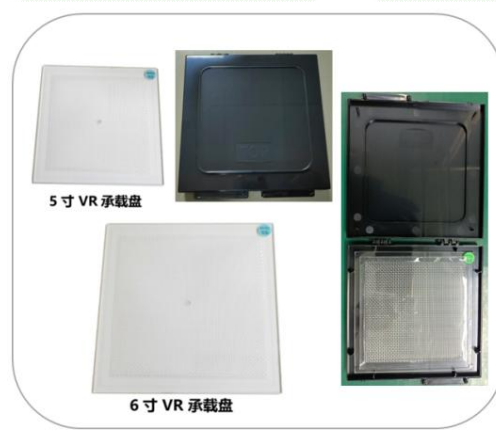
www.estecn.com



Precision Chip & Component Handling



VR Tray



Large Tray



Glue Box



Glue Tray



Glass Film



Film Box



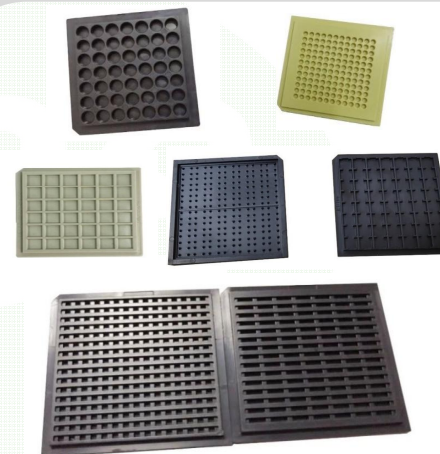
Precision Chip & Component Handling



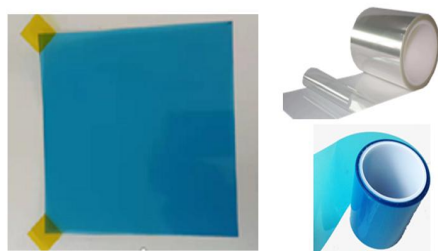
Grip
Ring



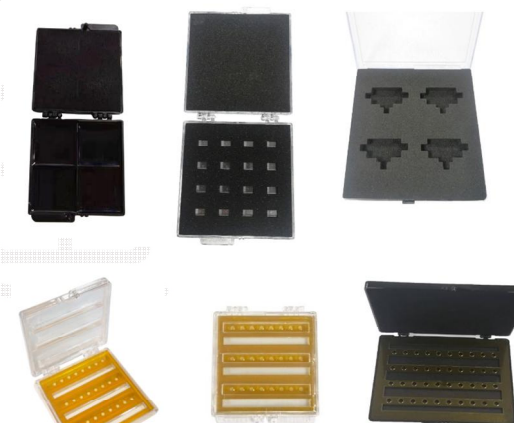
Waffle
Pack



GEL
Film

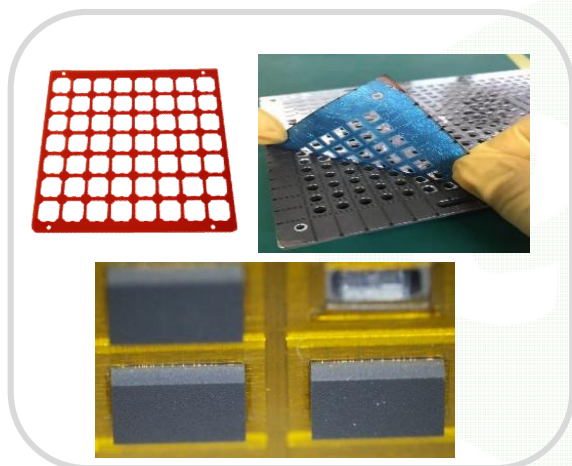


Foam
Box





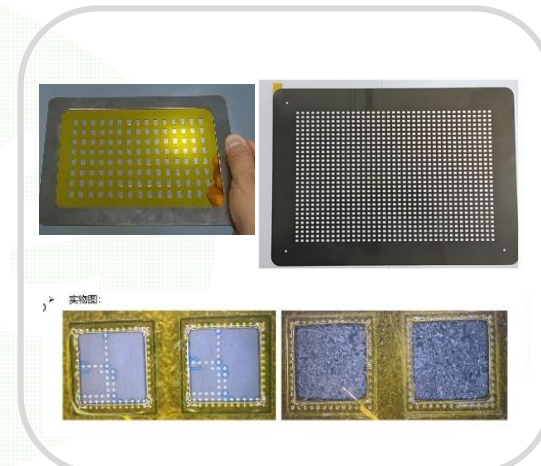
Semiconductor Process Materials - Sputter



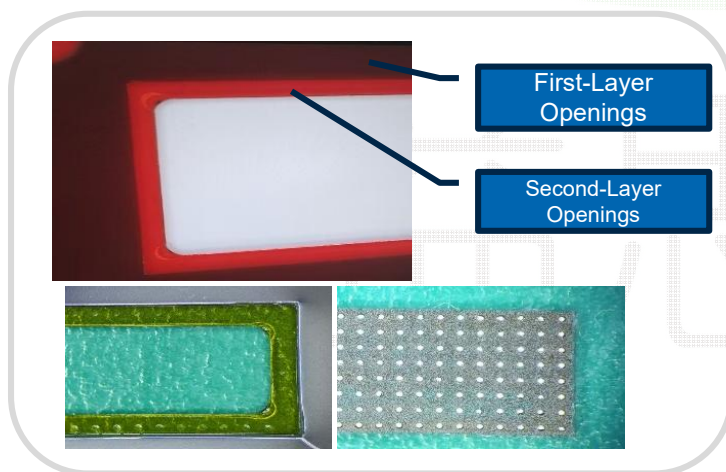
SP Tape — PI / VHB



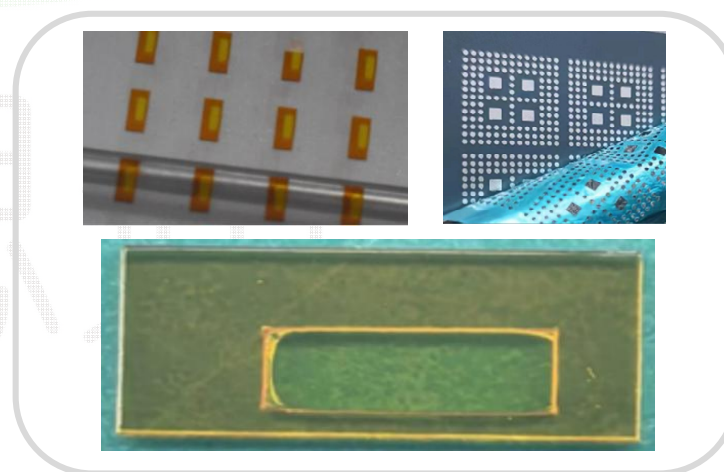
SP Tape — VHB / PI



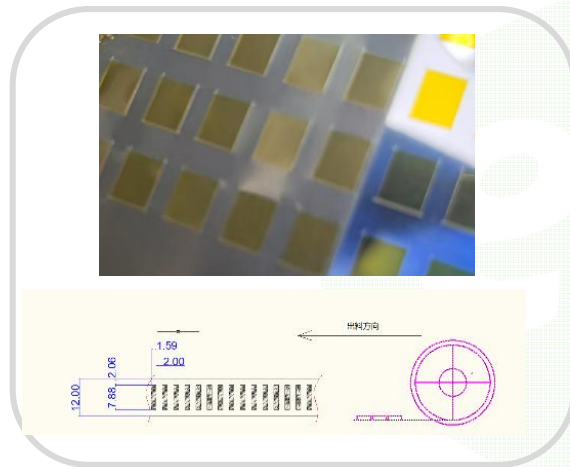
SP Tape — PET Film / PI Tape / VHB



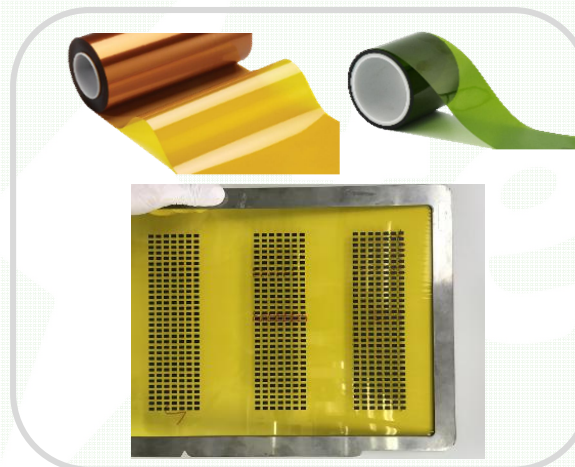
SP Tape — PET Tape / PI Tape / VHB



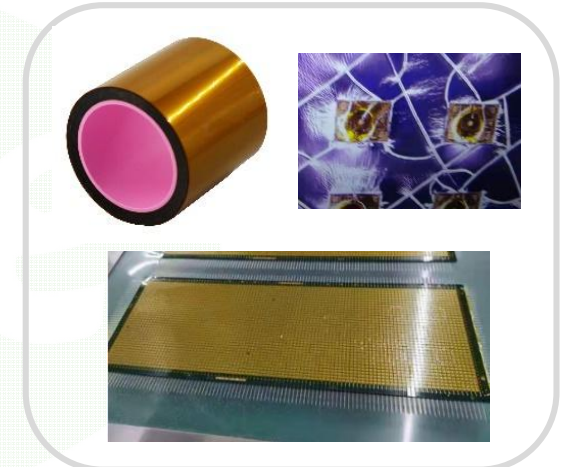
SP Tape — Die-Cut Masking Tape



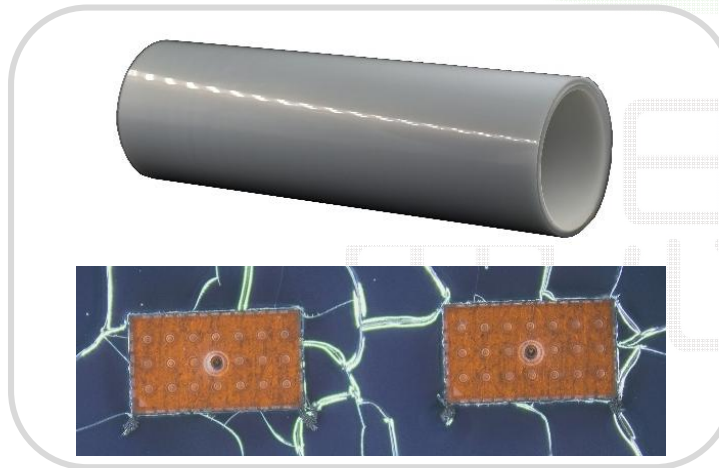
SP Tape — Single-Layer PI



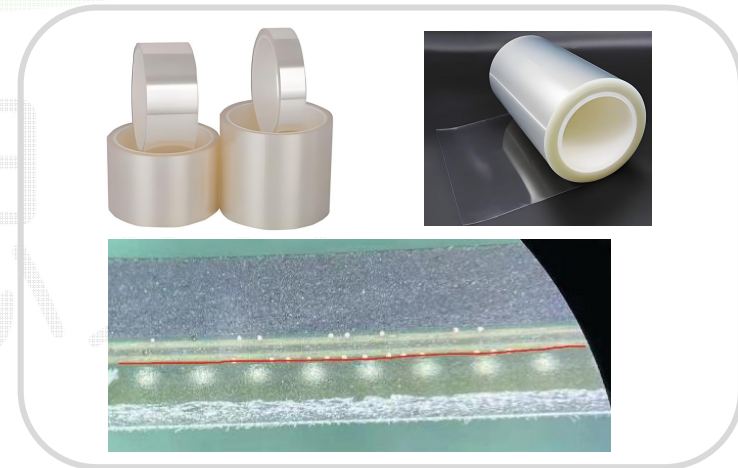
SP Tape — Ring Tape



SP Tape — Pre Tape



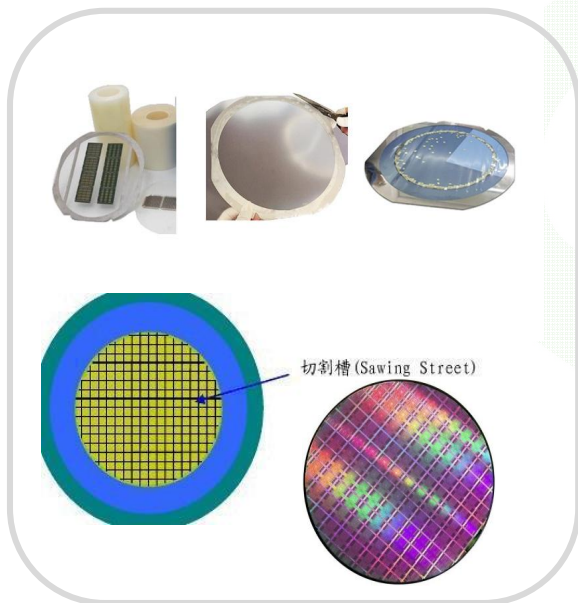
SP Tape — UV Tape



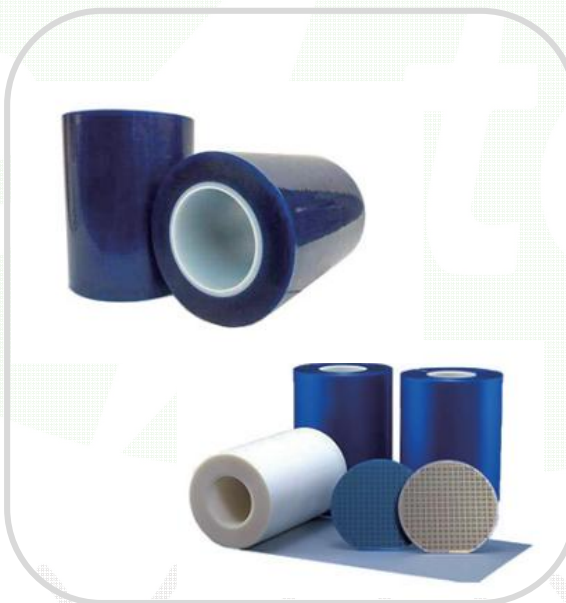
SP Tape — UV Pre Tape



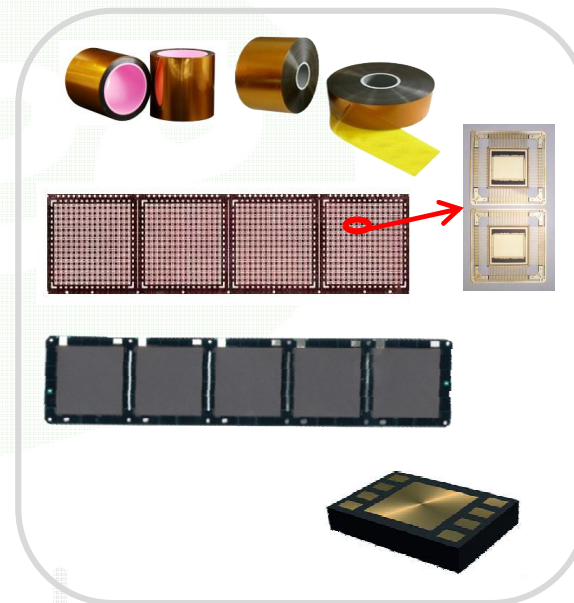
Semiconductor Process Materials - Wafer Packaging



UV Dicing Tape



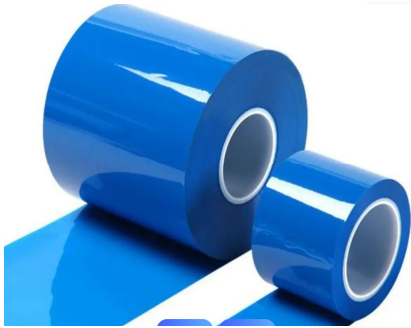
Blue Film



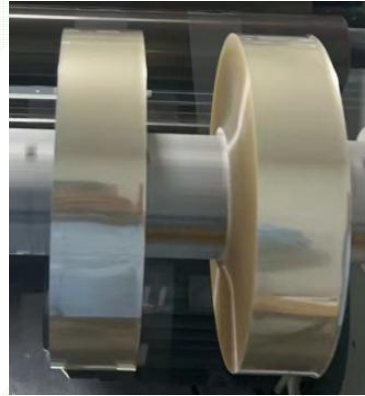
QFN Tape



Electronics Tapes & Precision Die Cutting - FPC



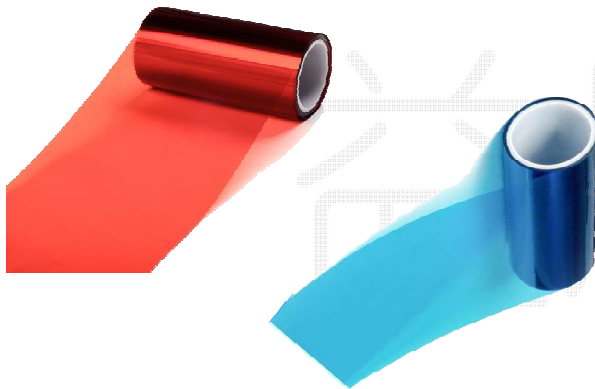
FPC Process Antistatic Film



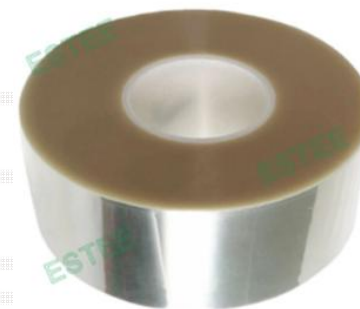
FPC High-/Low-Tack Tape



FPC Process TPU Film



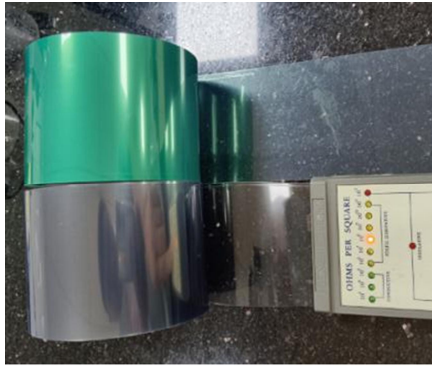
FPC Process Release Film



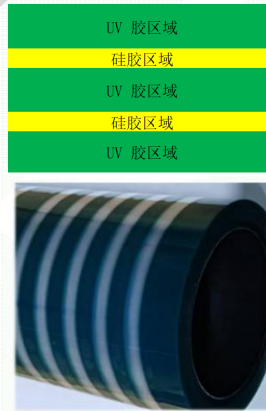
FPC Process Release Film



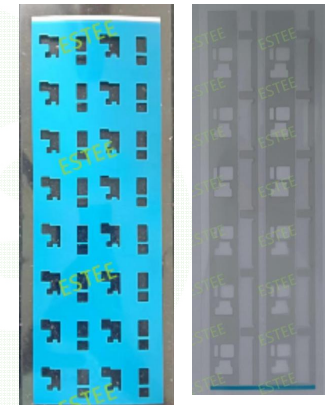
Electronics Tapes & Precision Die Cutting



PET Carrier Tape



UV
Combination
Tape



Tray Carrier Tape



High-Temp PET



Die-Cut



Electronics Tapes & Precision Die Cutting



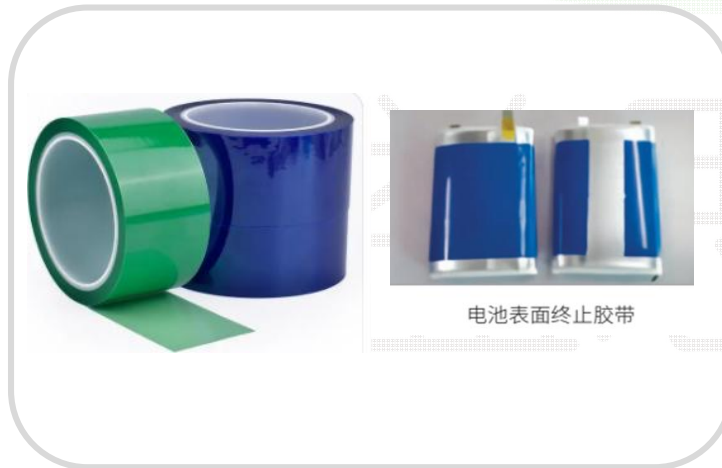
High-Temperature PI Tape



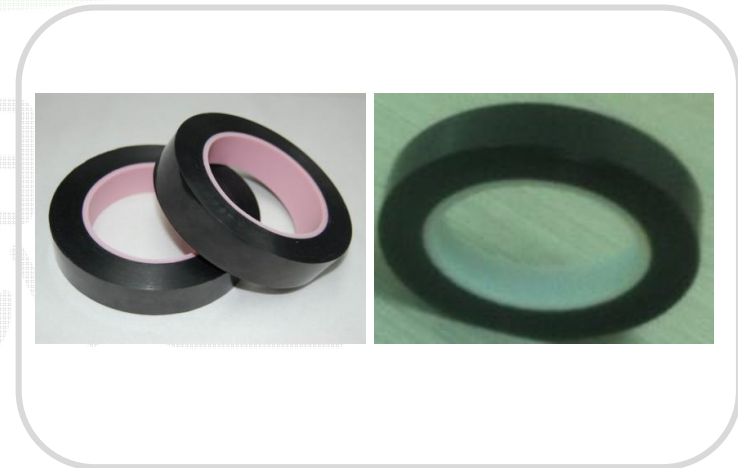
Identification Tape



Insulation Tape



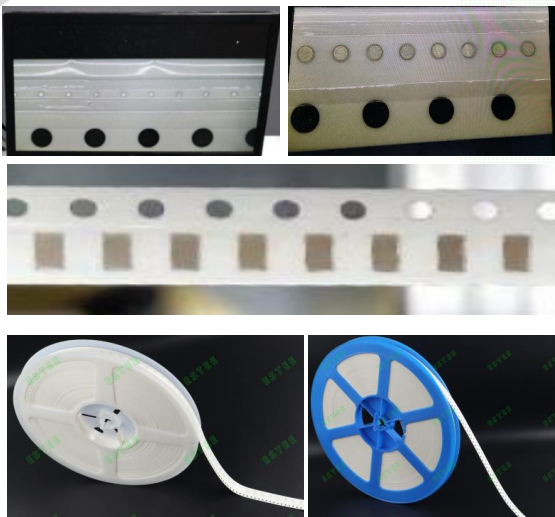
Acid- and Alkali-Resistant Tape



Antistatic Black Film

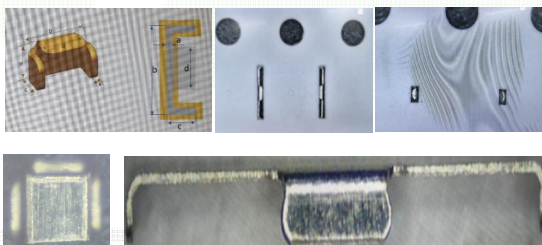


Precision Metal & Automated Packaging

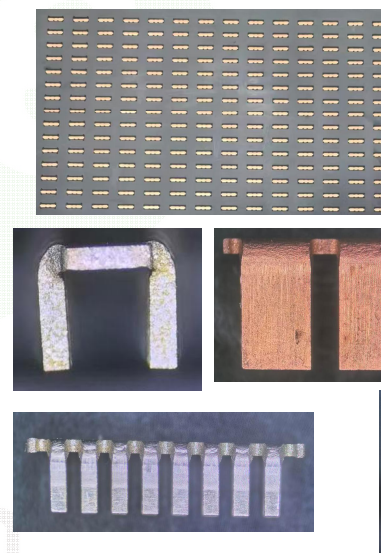


Micro-Precision Spacers

材料方案	材料设计尺寸				
	挡墙厚度 a(um)	挡墙长度 b(um)	引脚长度 c(um)	顶面长度 d(um)	挡墙高度 h(um)
方案1	50	500	210	400	450
方案2			300		
方案3			400		
方案4		3000	210	800	
方案5			300		
方案6			400		



EMI Shielding Walls



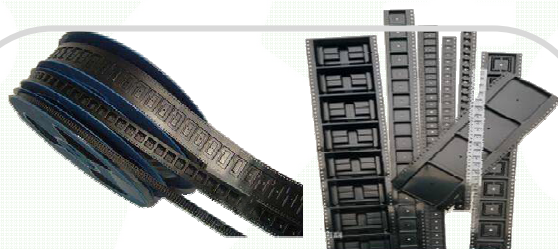
Copper Pillars



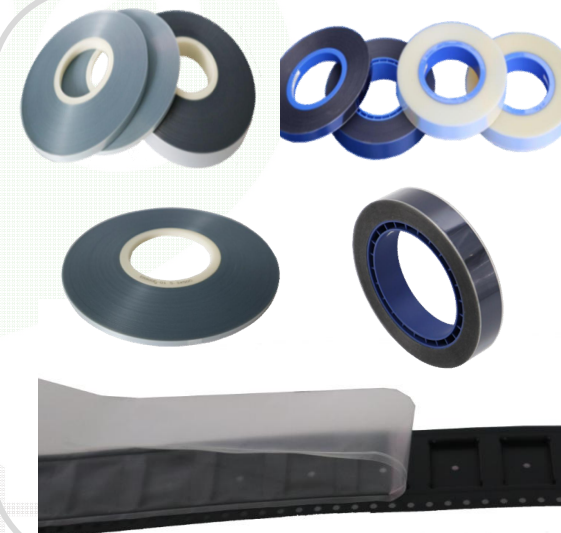
Precision Metal & Automated Packaging



Formed Paper Carrier Tape



Antistatic Plastic Carrier Tape



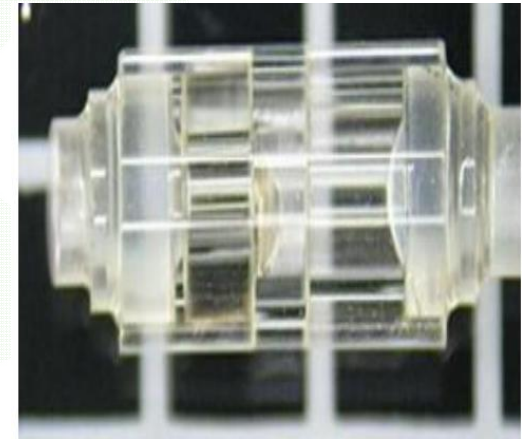
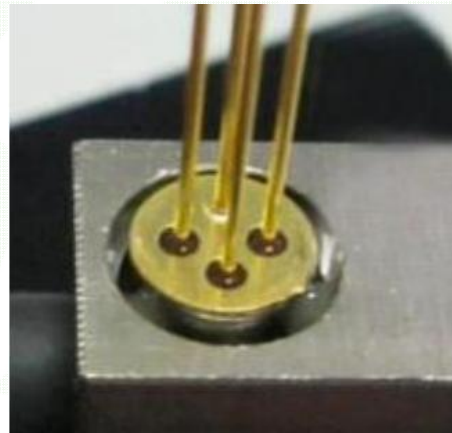
Antistatic Cover Tape



Industrial Adhesives & Bonding Solutions



- **Epoxy:** flexible and thermally conductive
- **Acrylic:** UV-curable adhesive
- **Silicone:** thermally conductive
- **PU:** UV-peelable adhesive





Smart ESD Systems & Services



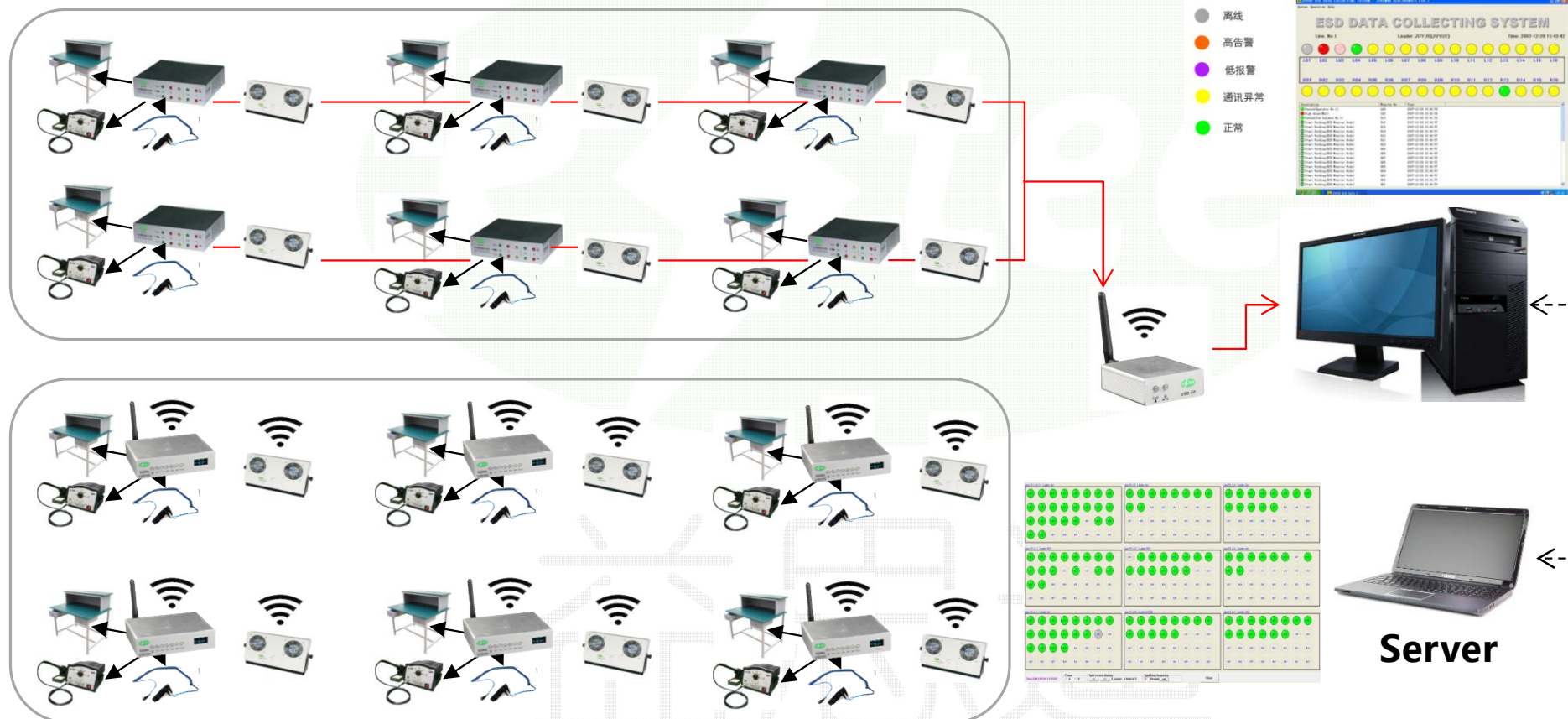
Smart Grounding
Monitoring
Equipment



Self-Balancing DC
Ionization Equipment



Smart ESD Systems & Services



Server-Based Global
Smart Monitoring

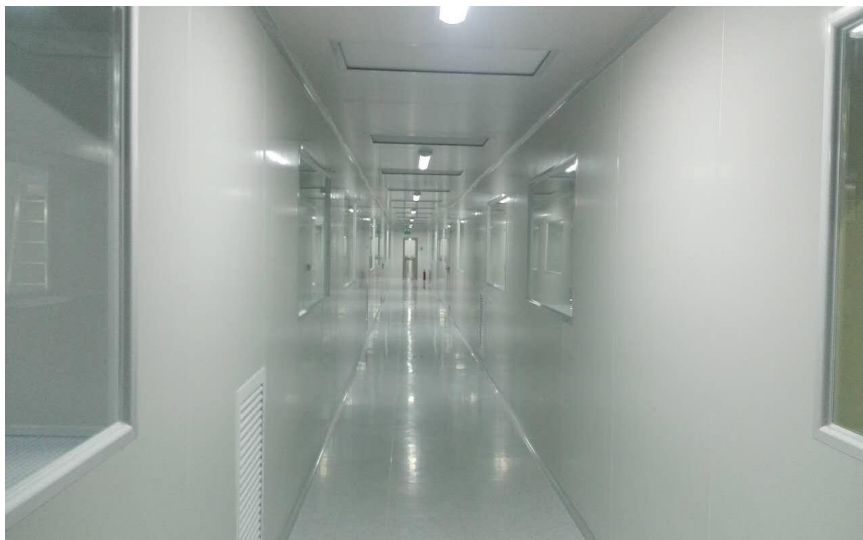


Factory Showroom





Cleanroom Coating Workshop & Equipment





Selected Die-Cutting Equipment



Workshop area: 2,500 m², including a 1,200 m² Class 1,000 cleanroom.



Product Testing Laboratory



Precision Oven



Tensile / Push-Force Tester



Tape Tack Tester



Tape Adhesion Test Chamber



Surface Resistance Meter



Electrostatic Voltmeter



Charged Plate Monitor



ESD Simulator



Product Testing Laboratory



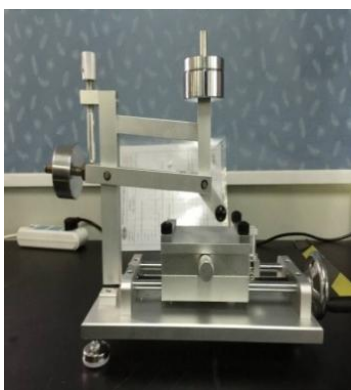
Contact Angle Goniometer



2.5D Vision Measuring System



Horizontal / Vertical
Flammability Tester



Hardness Tester



XRF Environmental Analyzer



Lab-X5000
Lab-X5000 XRF



Contact Us



www.estee.cn.com



0755-27659732 、 18025343367



marketing@estee.cn.com



THANK

SO

MUCH

YOU